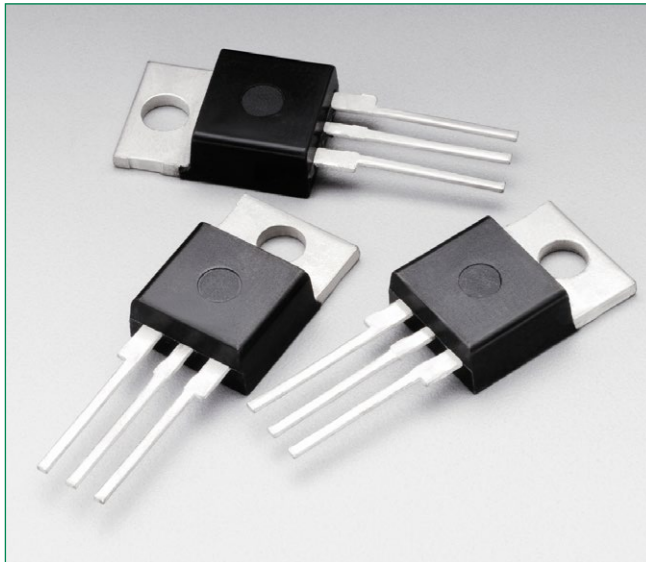


BTA25-600CW3G, BTA25-800CW3G



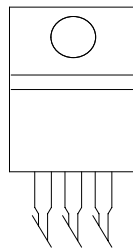
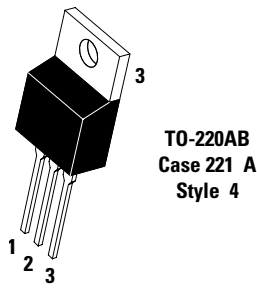
Description

Designed primarily for half-wave ac control applications, such as motor controls, heating controls and power supply crowbar circuits.

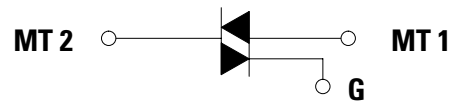
Features

- Blocking Voltage to 800 V
- On-State Current Rating of 25 A RMS at 25°C
- Uniform Gate Trigger Currents in Three Quadrants
- High Immunity to dV/dt – 500 V/ μ s minimum at 125°C
- Minimizes Snubber Networks for Protection
- Industry Standard TO-220AB Package
- High Commutating dI/dt – 14 A/ms minimum at 125°C
- Internally Isolated (2500 V_{RMS})
- These are Pb-Free Devices and are RoHS Compliant

Pin Out



Functional Diagram



Additional Information



Datasheet



Resources



Samples

Maximum Ratings ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off-State Voltage (Note 1) (Gate Open, Sine Wave 50 to 60 Hz, $T_J = -40^\circ$ to 125°C)	BTA25-600CW3G BTA25-800CW3G V_{DRM} V_{RRM}	600 800	V
On-State RMS Current (Full Cycle Sine Wave, 60 Hz, $T_C = 95^\circ\text{C}$)	$I_{T(RMS)}$	25	A
Peak Non-Repetitive Surge Current (One Full Cycle Sine Wave, 60 Hz, $T_C = 25^\circ\text{C}$)	I_{TSM}	250	A
Circuit Fusing Consideration ($t = 8.3$ ms)	I^2t	260	A ² sec
Non-Repetitive Surge Peak Off-State Voltage ($T_J = 25^\circ\text{C}$, $t = 8.3$ ms)	V_{DSM}/V_{RSM}	$V_{DSM}/V_{RSM} + 100$	V
Peak Gate Current ($T_J = 110^\circ\text{C}$, $t \leq 20\mu\text{s}$)	I_{GM}	4.0	W
Peak Gate Power (Pulse Width $\leq 20 \mu\text{s}$, $T_C = 80^\circ\text{C}$)	$P_{G(AV)}$	20	W
Average Gate Power ($T_J = 110^\circ\text{C}$)	$P_{G(AV)}$	1.0	W
Operating Junction Temperature Range	T_J	-40 to +125	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-40 to +125	$^\circ\text{C}$
RMS Isolation Voltage ($t = 300$ ms, R.H. $\leq 30\%$, $T_A = 25^\circ\text{C}$)	V_{iso}	2500	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

Thermal Characteristics

Rating	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (AC) Junction-to-Ambient	$R_{\theta JC}$ $R_{\theta JA}$	2.13 60	$^\circ\text{C}/\text{W}$
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	T_L	260	$^\circ\text{C}$

Electrical Characteristics - OFF ($T_J = 25^\circ\text{C}$ unless otherwise noted ; Electricals apply in both directions)

Characteristic	Symbol	Min	Typ	Max	Unit
Peak Repetitive Blocking Current ($V_D = V_{DRM} = V_{RRM}$; Gate Open)	I_{DRM} I_{RRM}	-	-	0.005	mA
		-	-	2.0	

Electrical Characteristics - ON ($T_J = 25^\circ\text{C}$ unless otherwise noted; Electricals apply in both directions)

Characteristic	Symbol	Min	Typ	Max	Unit
Forward On-State Voltage (Note 2) ($I_{TM} = \pm 22.5$ A Peak)	V_{TM}	-	-	1.55	V
Gate Trigger Current (Continuous dc) ($V_D = 12$ V, $R_L = 30 \Omega$)	MT2(+), G(+)	2.0	-	35	mA
	MT2(+), G(-)	2.0	-	35	
	MT2(-), G(-)	2.0	-	35	
Holding Current ($V_D = 12$ V, Gate Open, Initiating Current = ± 500 mA)	IH	-	-	50	mA
Latching Current ($V_D = 12$ V, $I_G = 12$ mA)	MT2(+), G(+)	-	-	75	mA
	MT2(+), G(-)	-	-	75	
	MT2(-), G(-)	-	-	75	
Gate Trigger Voltage ($V_D = 12$ V, $R_L = 30 \Omega$)	MT2(+), G(+)	0.5	-	1.3	V
	MT2(+), G(-)	0.5	-	1.3	
	MT2(-), G(-)	0.5	-	1.3	
Gate Non-Trigger Voltage ($T_J = 110^\circ\text{C}$)	MT2(+), G(+)	0.2	-	-	V
	MT2(+), G(-)	0.2	-	-	
	MT2(-), G(-)	0.2	-	-	

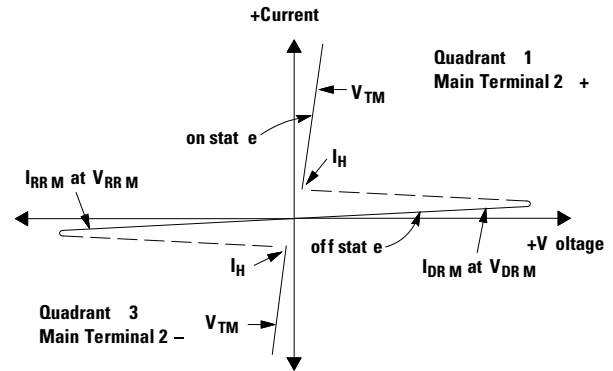
2. Indicates Pulse Test: Pulse Width ≤ 2.0 ms, Duty Cycle $\leq 2\%$.

Dynamic Characteristics

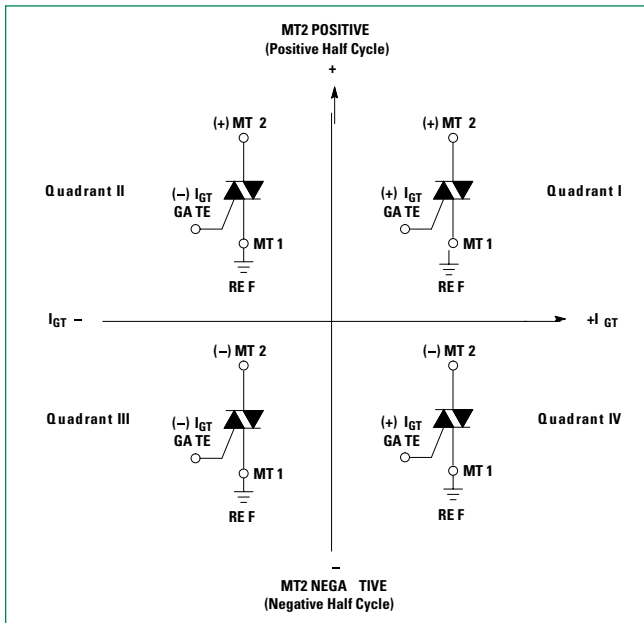
Characteristic	Symbol	Min	Typ	Max	Unit
Rate of Change of Commutating Current, See Figure 10. (Gate Open, $T_j = 110^\circ\text{C}$, No Snubber)	$(di/dt)_c$	2.0	-	-	A/ms
Critical Rate of Rise of On-State Current ($T_j = 110^\circ\text{C}$, $f = 120\text{ Hz}$, $I_g = 20\text{ mA}$, $t_r \leq 100\text{ ns}$)	di/dt	-	-	50	A/ μs
Critical Rate of Rise of Off-State Voltage ($V_D = 0.66 \times V_{DRM}$, Exponential Waveform, Gate Open, $T_j = 110^\circ\text{C}$)	dV/dt	250	-	-	V/ μs

Voltage Current Characteristic of SCR

Symbol	Parameter
V_{DRM}	Peak Repetitive Forward Off State Voltage
I_{DRM}	Peak Forward Blocking Current
V_{RRM}	Peak Repetitive Reverse Off State Voltage
I_{RRM}	Peak Reverse Blocking Current
V_{TM}	Maximum On State Voltage
I_H	Holding Current



Quadrant Definitions for a Triac



All polarities are referenced to MT1
With in-phase signals (using standard AC lines) quadrants I and III are used.

Figure 1. RMS Current Derating

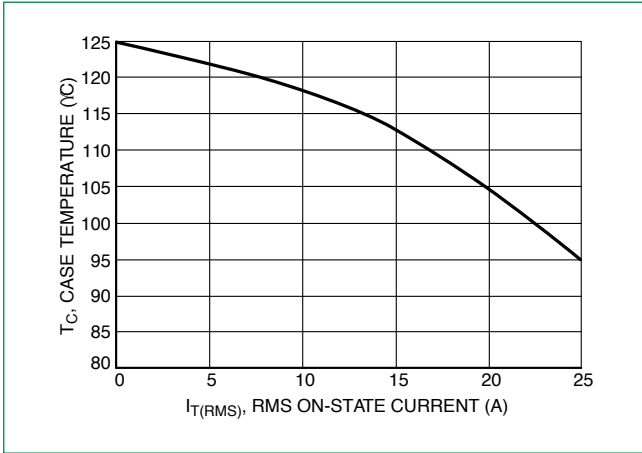


Figure 2. On-State Power Dissipation

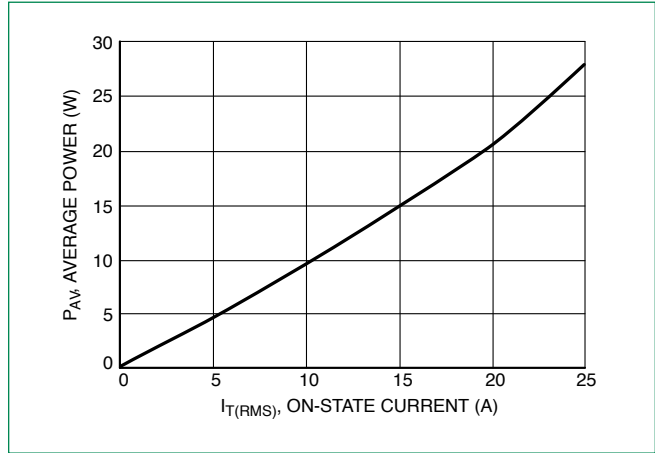


Figure 3. On-State Characteristics

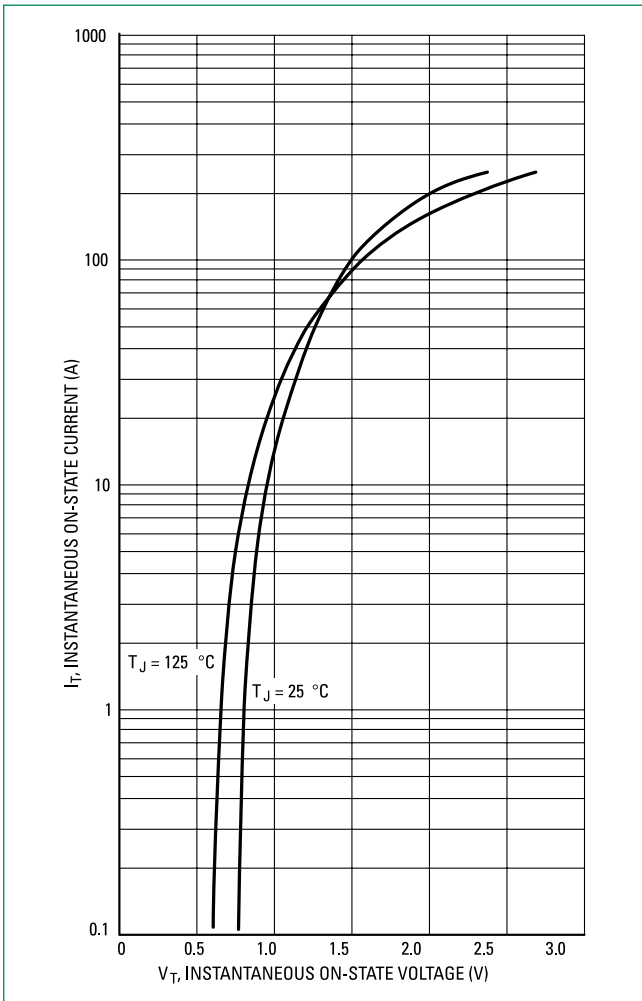


Figure 4. Thermal Response

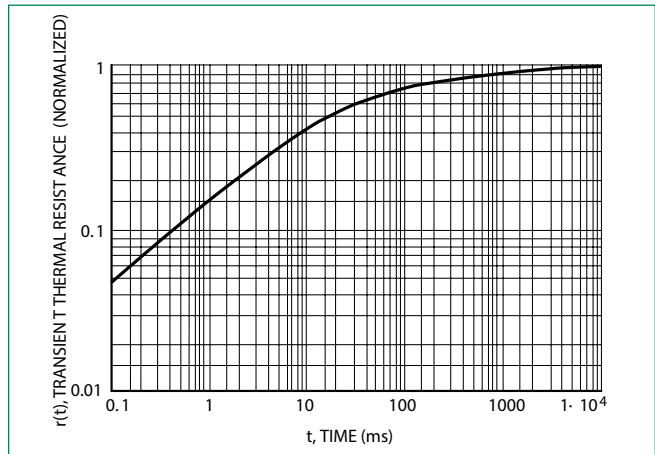


Figure 5. Hold Current Variation

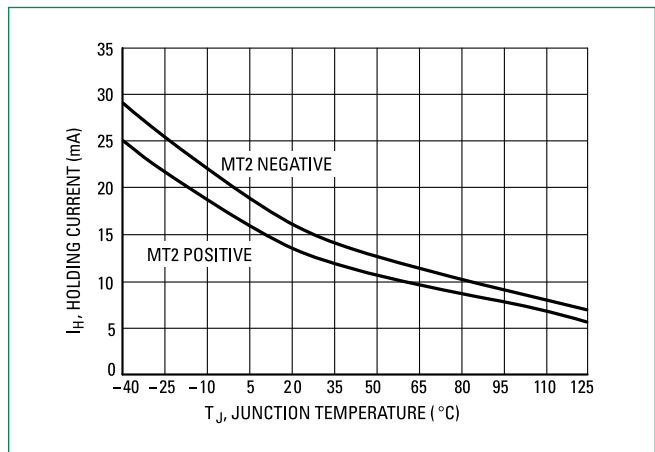


Figure 6. Gate Trigger Current Variation

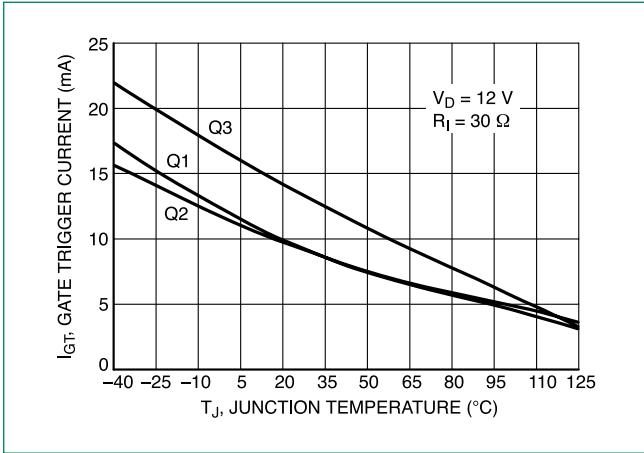


Figure 7. Gate Trigger Voltage Variation

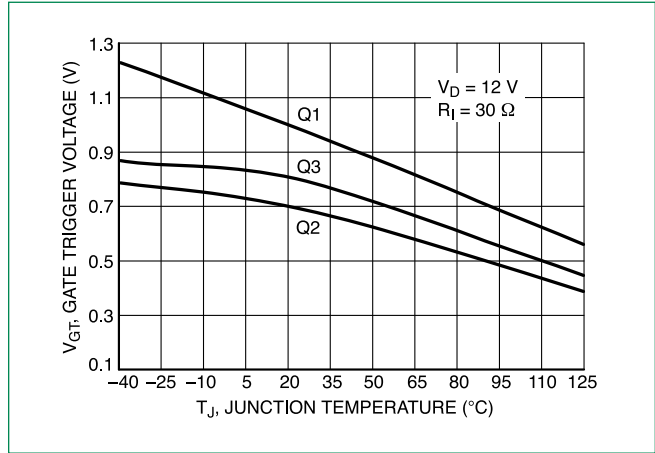


Figure 8. Critical Rate of Rise of Off-State Voltage (Exponential Waveform)

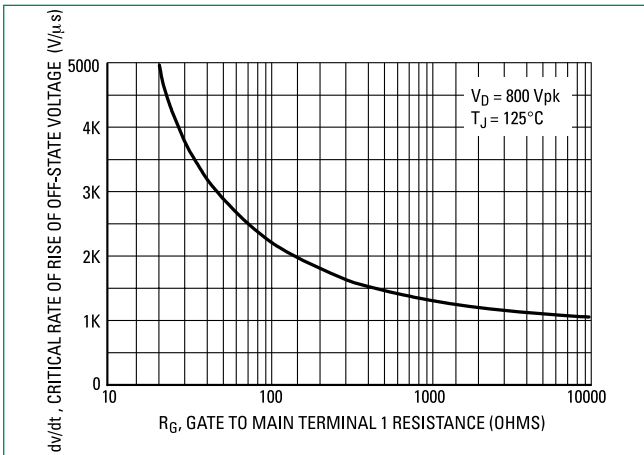


Figure 9. Latching Current Variation

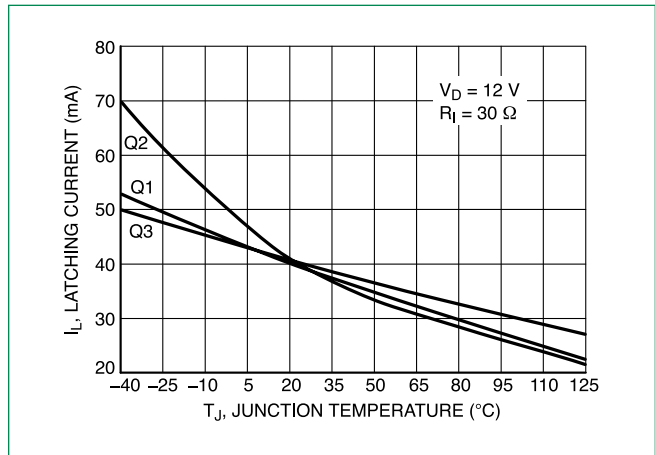
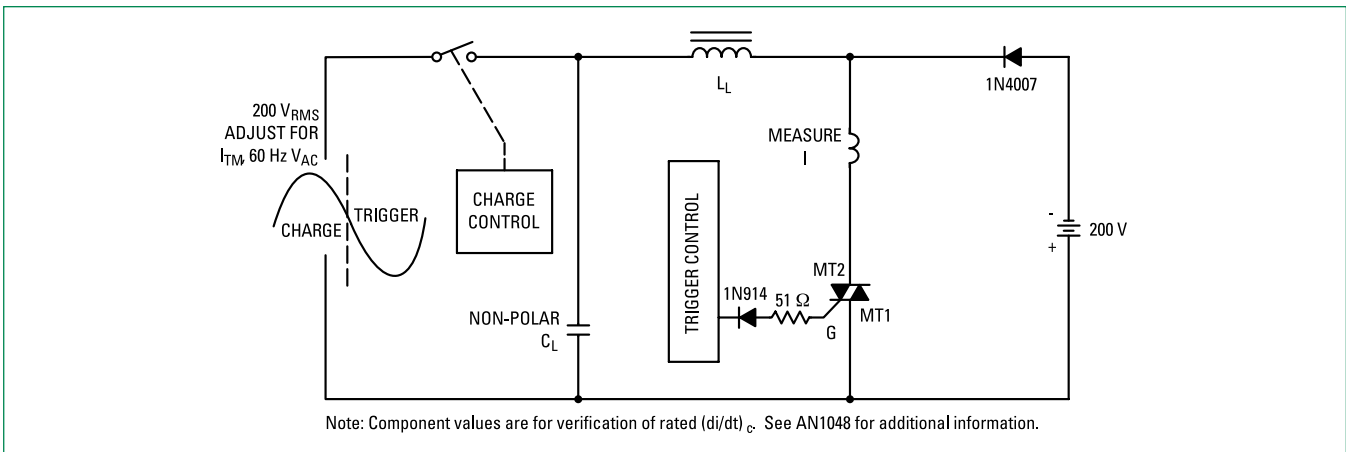
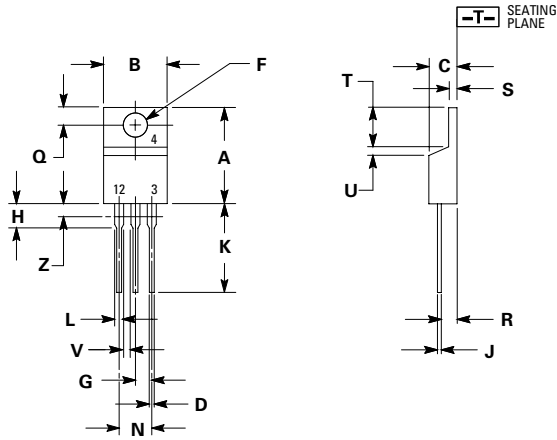


Figure 10. Simplified Test Circuit to Measure the Critical Rate of Rise of Commutating Current (di/dt)



Dimensions

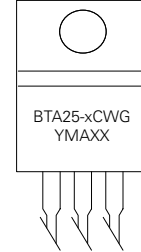


Part Marking System



**TO-220AB
CASE 221A
STYLE 12**

x = 6 or 8
Y = Year
M = Month
A = Assembly Site
XX = Lot Serial Code
G = Pb-Free Package



Dim	Inches		Millimeters	
	Min	Max	Min	Max
A	0.590	0.620	14.99	15.75
B	0.380	0.420	9.65	10.67
C	0.178	0.188	4.52	4.78
D	0.025	0.035	0.64	0.89
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.41	2.67
H	0.110	0.130	2.79	3.30
J	0.018	0.024	0.46	0.61
K	0.540	0.575	13.72	14.61
L	0.060	0.075	1.52	1.91
N	0.195	0.205	4.95	5.21
Q	0.105	0.115	2.67	2.92
R	0.085	0.095	2.16	2.41
S	0.045	0.060	1.14	1.52
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045	—	1.15	—
Z	—	0.080	—	2.04

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

Pin Assignment	
1	Main Terminal 1
2	Main Terminal 2
3	Gate
4	No Connection

Ordering Information

Device	Package	Shipping
BTA25-600SW3G	TO-220AB (Pb-Free)	500 Units / Rail
BTA25-800SW3G	TO-220AB (Pb-Free)	500 Units / Rail

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